

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
Contact Info: ti.com/support
Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
Created on: 05/30/2022

Details for "INA116UAG4"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
INA116UAG4	NIPDAU-DCC	Level-3-260C-168 HR	TI TAIWAN A/T	DW 16	7.52x10.28x2.35	477.4

*Total Device Mass
The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component		Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
					Percentage %	ppm	Percentage %	ppm
Bond Wire								
Copper and Its Alloys	Copper	7440-50-8	0.000001	0.00022	2		0	0
Copper and Its Alloys	Iron	7439-89-6	0.000001	0.00022	2		0	0
Precious Metals	Gold	7440-57-5	0.451386	99.376073	993761	0.094547	945	
Precious Metals	Palladium	7440-05-3	0.002827	0.622386	6224	0.000592	6	
Precious Metals	Silver	7440-22-4	0.000005	0.001101	11	0.000001	0	
Sub-Total			0.45422	100	1000000	0.095141	951	
Die Attach Adhesive								
Other Inorganic Materials	Silica	7631-86-9	0.033224	1.999988	20000	0.006959	70	
Precious Metals	Silver	7440-22-4	1.146235	69.000006	690000	0.24009	2401	
Thermoplastics	Epoxy	85954-11-6	0.481751	29.000006	290000	0.100907	1009	
Sub-Total			1.66121	100	1000000	0.347957	3480	
Lead Frame								
Copper and Its Alloys	Copper	7440-50-8	133.4517	97.41	974100	27.952751	279528	
Copper and Its Alloys	Iron	7439-89-6	3.288	2.4	24000	0.688703	6887	
Copper and Its Alloys	Phosphorus	7723-14-0	0.0411	0.03	300	0.008609	86	
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.0411	0.03	300	0.008609	86	
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.0411	0.03	300	0.008609	86	
Zinc and Its Alloys	Zinc	7440-66-6	0.137	0.1	1000	0.028696	287	
Sub-Total			137	100	1000000	28.695977	286960	
Lead Frame Plating								
Nickel and Its Alloys	Nickel	7440-02-0	2.345659	95.119992	951200	0.491321	4913	
Precious Metals	Gold	7440-57-5	0.019235	0.780008	7800	0.004029	40	
Precious Metals	Palladium	7440-05-3	0.101106	4.1	41000	0.021178	212	
Sub-Total			2.466	100	1000000	0.516528	5165	
Mold Compound								
Other Inorganic Materials	Fused Silica	60676-86-0	284.149686	86	860000	59.517904	595179	
Other Plastics and Rubber	Carbon Black	1333-86-4	0.99122	0.3	3000	0.207621	2076	
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	1.817236	0.55	5500	0.380638	3806	
Thermoplastics	Epoxy	85954-11-6	43.448469	13.15	131500	9.100703	91007	
Sub-Total			330.406611	100	1000000	69.206865	692069	
Semiconductor Device								
Ceramics / Glass	Doped Silicon	7440-21-3	5.430794	100	1000000	1.137532	11375	
Sub-Total			5.430794	100	1000000	1.137532	11375	
Total				477.418835			100	1000000

Important Note
The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information
There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSiS or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer
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[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.